



Product Change Notification

Change Notification #: 118026 - 00
Change Title: Intel® Server System S9232WK2HAC,
Intel® Server System S9248WK2HAC,
PCN 118026-00, Product Material,
Added e-clip on Heatsink
Date of Publication: January 7, 2021

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 22, 2021
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel

Description of Change to the Customer:

Intel is adding an “e-clip” to the heatsinks included in the Intel products in table “Product Affected”. The “e-clip” is shown in figure 2. e-clip heatsink.

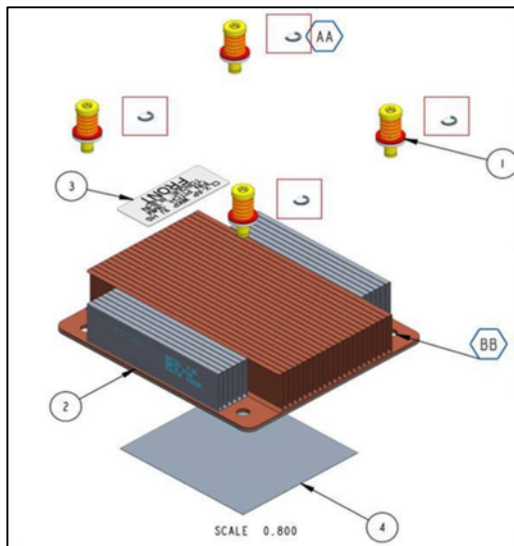


Figure 1. heatsink before change

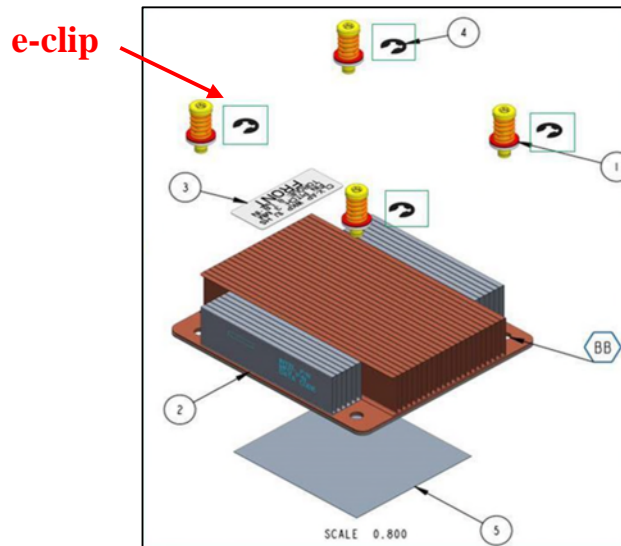


Figure 2. heatsink with “e-clip”

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes described but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
S9232WK2HAC	999DA6	K26069-005	K26069-006
S9248WK2HAC	999DA4	K24476-006	K24476-007

PCN Revision History:

Date of Revision:

January 7, 2021

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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